



DEVICE TYPE:				<b>SEMPAC, INC.</b> Open-Pak™ Technologies <a href="http://www.sempac.com">www.sempac.com</a> 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006					
CUSTOMER:			DIE SIZE:						
WIRE TYPE/ SIZE:			NO. OF WIRES:						
 THIRD ANGLE PROJECTION	REVISIONS					28 Lead 5mm x 5mm MLP Open-Pak Bonding Diagram			
	ECN NO.	DATE	DESCRIPTION	APPROVED					
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING	10483	10/27/05	PRODUCTION RELEASE	D.BENANDO		SIZE	PART NO.	REV	
DRAWN BY W. GRIFFITTS	DATE	07/28/05	PACKAGE SIZE:	5.00mm x 5.00mm	SCALE	A	MLP5X5-28-OP-01	2	
APP BY P. FLASKERUD	DATE	07/28/05	DIE PAD SIZE:	3.10mm x 3.10mm	CAD FILE	MLP5X5-28-OP-01-B-R2.DWG	SHEET 1 OF 1		